

#### ABSTRACT OF THE DISCLOSURE

Provided are a method for manufacturing a mounting substrate and a method for manufacturing a circuit device, both of which include the step of electroplating a number of electrodes. The method for manufacturing a mounting substrate includes the steps of: forming a plurality of electrodes to a mounting substrate, the plurality of electrodes being electrically connected to each other by use of plating wires; energizing the electrodes via the plating wires to coat the electrodes with plated films 19 by electroplating; and electrically separating the individual electrodes from each other by cutting off the plating wires. Furthermore, the method for manufacturing a circuit device includes, in addition to the foregoing method for manufacturing a mounting substrate, the steps of: fixing a circuit element on the mounting substrate and electrically connecting the electrodes with the circuit element; and forming a sealing resin so as to cover the circuit element.